

Amendments to the Specification

Please replace paragraph [0002] with the following amended paragraph:

[0002] This application is related to U.S. Application No. 10/632,549, titled “Semiconductor multi-package module having wire bond interconnect between stacked packages”; U.S. Application No. 10/632,568, titled “Semiconductor multi-package module having package stacked over ball grid array package and having wire bond interconnect between stacked packages”; U.S. Application No. 10/632,551, titled “Semiconductor multi-package module having wire bond interconnect between stacked packages and having electrical shield”, which issued on January 4, 2005 as U.S. Patent No. 6,838,761; U.S. Application No. 10/632,552, titled “Semiconductor multi-package module having package stacked over die-up flip chip ball grid array package and having wire bond interconnect between stacked packages”; U.S. Application No. 10/632,553, titled “Semiconductor multi-package module having package stacked over die-down flip chip ball grid array package and having wire bond interconnect between stacked packages”; U.S. Application No. 10/632,550, titled “Semiconductor multi-package module including stacked-die packages and having wire bond interconnect between stacked packages”. This application and all the said related applications are being filed on the same date, and each of the said related applications is hereby incorporated herein by reference.

Please replace paragraph [0068] with the following amended paragraph:

[0068] In the top LGA package in the embodiment of FIG. 5A the die is wire bonded onto wire bond sites on the upper metal layer of the substrate to establish electrical connections. The die 514 and the wire bonds 516 are encapsulated with a molding compound 517 that provides protection from ambient and from mechanical stress to facilitate handling operations, and has a top package upper surface 519. The top package 500 is stacked over the bottom package 400 and affixed there using an adhesive [[513]] 503. Solder masks 515, 527 are patterned over the metal layers 521, 523 to expose the underlying metal at bonding sites for electrical connection, for example the wire bond sites for bonding the wire bonds 516..